PATENT

3/08/01 09800574

Docket No.: NAU019-1

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

## RECORDING COVER SHEET

1. Assignor:

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2. Assignee:

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Hsin-Chu, Taiwan, R.O.C.

3. Nature of Conveyance: Assignment of patent

Reference number:

Application filed herewith.

5. Correspondence to:

Winston Hsu

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6. Number of applications affected by this recording: 1

Total fee:  $(1 \times \$ 40) = \$ 40.00$  Payment by check enclosed Authorization is hereby given to charge the over payment to deposit account #500801

- 7. Execution date of the document to be recorded: 03/05/2001
- 8. Total number of pages including cover sheet: 3
- 9. I declare under penalty of perjury that to the best of my knowledge and belief, the information contained on this cover sheet is true and correct, and that any copy submitted herewith is a true and correct copy of the original document.

Date:

3/6/2001

Winston Hou

Winston Hsu U.S. Patent Agent Reg. No.:41,526

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PATENT

REEL: 011608 FRAME: 0979

## **ASSIGNMENT OF INVENTION**

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration,

**ASSIGNORS (Inventors):** 

Name:	Hermen Liu	Nationality:	R.O.C
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Name:		_ Nationality: _	
Address:			
Name:		_ Nationality: _	
Address:			
Hereby s	ells, assigns and transfers tol	UNITED MICK	DELECTRONICS CORP.
•	fter "Assignee"), of (Assignee add		
Industr	<u>ial Park, Hsin-Chu, Taiwan, R</u>	.O.C., and the s	successors assigns and legal
	tatives of the ASSIGNEE the enti		
	vements which are disc		
"Bo	nding pad on a semiconductor cl	nip.	· · · · · · · · · · · · · · · · · · ·
Which is	s found in :		
	U.S. patent application execute	ed on even date here	ewith
	U.S. patent application execute		
	U.S. application serial no.		
	patent no.		

Page 1 of 2

PATENT REEL: 011608 FRAME: 0980 and, in and to, all Letters Patent to be obtained for said invention by the above application or ant continuation, division, renewal, or substitute thereof, and as to letters patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this  $\frac{3/31}{1969}$  (Date of signing).

(Type name of inventor)	Signature of INVENTOR		
Hermen Liu	Hermen Lin 3/51/99		
Yimin Huang	yinin Huang 31 Mar. 1919		

Assignment, Page 2 of 2

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RECORDED: 03/08/2001